



Material Content Data Sheet



Sales Product Name	TLE75602-ESD			Issued	1. August 2018			
MA#	MA001709394							
Package	PG-TSDSO-24-21			Weight*	796.89 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	0.39	0.39	3882	3882
leadframe	inorganic material	phosphorus	7723-14-0	0.064	0.01		80	
	non noble metal	zinc	7440-66-6	0.256	0.03		321	
	non noble metal	iron	7439-89-6	5.116	0.64		6421	
wire	non noble metal	copper	7440-50-8	207.751	26.07	26.75	260703	267525
	non noble metal	copper	7440-50-8	0.939	0.12	0.12	1178	1178
	encapsulation	organic material	carbon black	1333-86-4	1.724	0.22		2163
encapsulation	plastics	epoxy resin	-	67.228	8.44		84363	
	inorganic material	silicondioxide	60676-86-0	505.646	63.45	72.11	634527	721053
leadfinish	non noble metal	tin	7440-31-5	3.642	0.46	0.46	4571	4571
plating	noble metal	silver	7440-22-4	0.339	0.04	0.04	425	425
glue	plastics	epoxy resin	-	0.190	0.02		239	
	noble metal	silver	7440-22-4	0.898	0.11	0.13	1127	1366
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com